MSV

S2M

Surface Mount General Purpose Silicon

FEATURES
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA
- Case: SMA

Top View
Marking Code : S2M
Simplified outline SMA and symbol

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Maximum Ratings and Electrical characteristics

Parameter	Symbols	S2M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	50	A
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.1	V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 100	μA
Typical Junction Capacitance (1)	C_j	25	pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	65	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

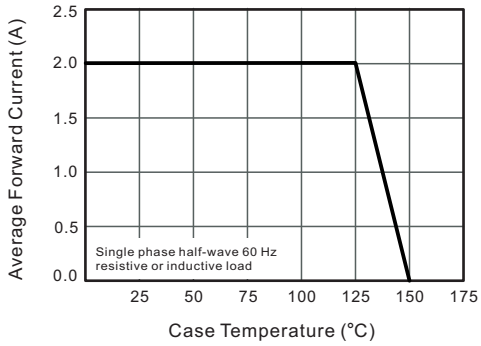


Fig.2 Typical Reverse Characteristics

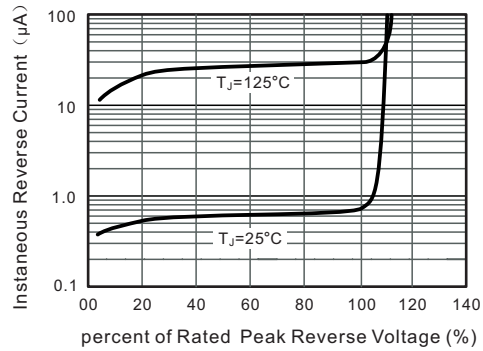


Fig.3 Typical Forward Characteristic

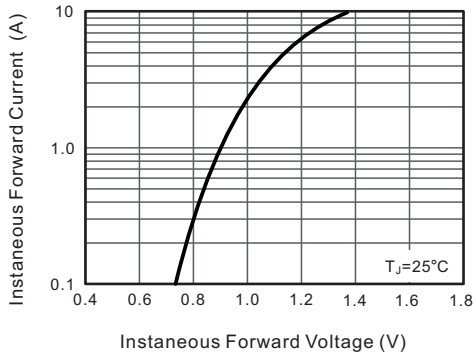


Fig.4 Typical Junction Capacitance

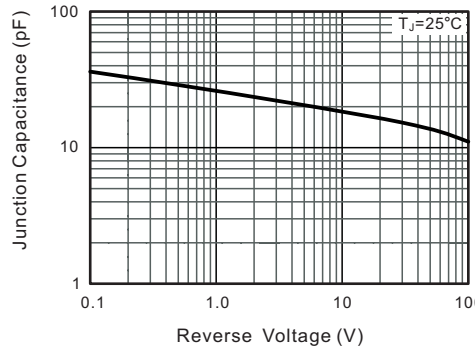
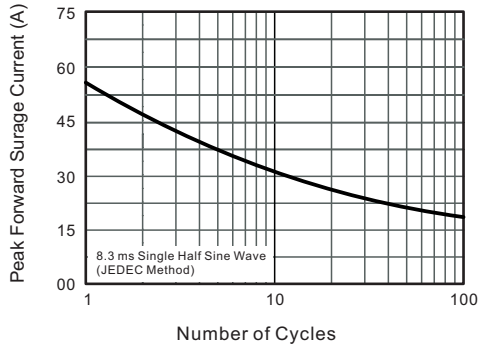


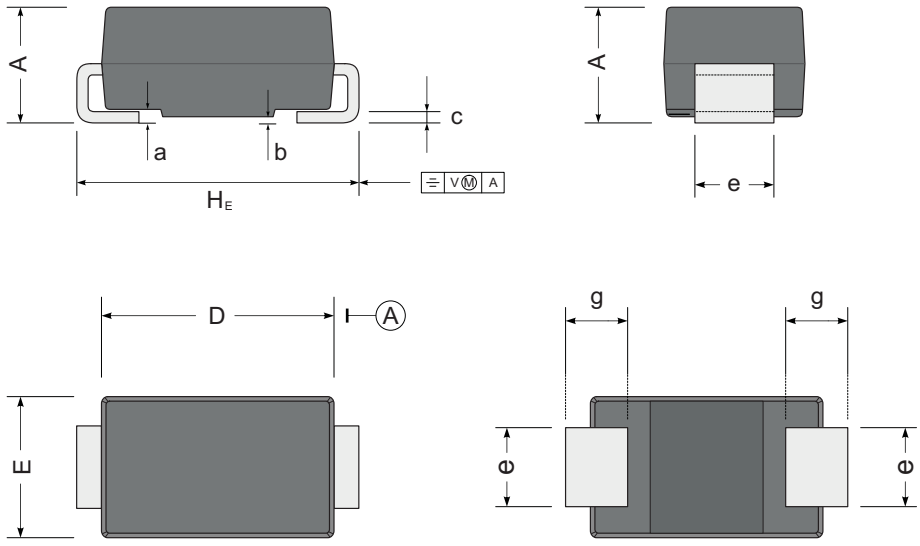
Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



PACKAGE OUTLINE

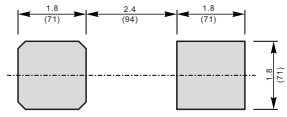
Plastic surface mounted package; 2 leads

SMA



UNIT		A	D	E	H_E	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

The recommended mounting pad size



Unit : mm (mil)